

AMENDMENTS TO THE CLAIMS

Listing of the claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

1. (Currently Amended) A component in a film forming equipment for forming a thin film on a substrate, the component having a matrix material and being subject to formation on a surface of the component, during thin film formation, of a deposited film comprising a film forming material, the component being taken out of the film forming equipment for dipping in a cleaning fluid to remove the deposited film, the component having:

[[and]] a first metal film layer electrochemically less noble than the matrix material in the cleaning liquid, thereby forming a local cell, when dipped in the cleaning liquid, between the matrix material and the first metal layer, the first metal film layer being formed on a surface of the matrix material through one of: thermal spraying, vapor depositing, sputtering, and laminating; and

a second metal film layer formed on the surface of the first metal film layer, the second metal film layer being electrochemically more noble than the matrix material in the cleaning liquid, thereby forming a local cell, when dipped in the cleaning liquid, between the first metal film layer, the second metal film layer being formed through one of: thermal spraying, vapor depositing, sputtering, and laminating.

2. (Cancelled)

3. (Withdrawn) A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.

4. (Withdrawn) The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.

5. (New) A component in a film forming equipment for forming a thin film on a substrate, the component having:

a matrix material;

a means on said matrix material for forming a local cell, when exposed to a cleaning liquid, with the matrix material so that a local current flows from the matrix material thereby advancing dissolution of the means at an interface between the means and the matrix material and allowing the removal of a film layer of the thin film from the matrix material.

6. (New) A component in a film forming equipment for forming a thin film on a substrate, the component having:

a matrix material;

a first means on said matrix material for forming a first local cell, when exposed

to a cleaning liquid, with the matrix material so that a first local current flows from the matrix material thereby advancing dissolution of the first means at an interface between the first means and the matrix material and allowing the removal of a film layer of the thin film from the matrix material; and

a second means on said first means forming a second local cell, when exposed to a cleaning liquid, so that a second local current flows from the second means thereby advancing dissolution of the first means at an interface between the first means and the second means and allowing the removal of the film layer of the thin film from the matrix material.